

# TM12N02S

## N-Channel Enhancement Mosfet

### General Description

- Low  $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

### Applications

- Load switch
- PWM

### General Features

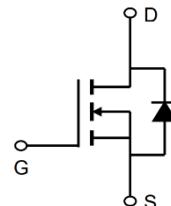
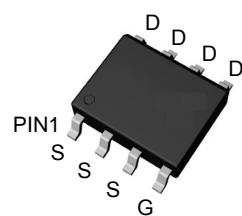
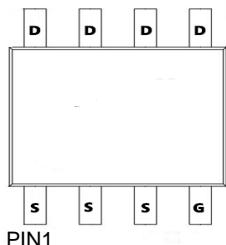
$V_{DS} = 20V$   $I_D = 12A$

$R_{DS(ON)} = 8m\Omega$  (typ.) @  $V_{GS} = 4.5V$

100% UIS Tested  
100%  $R_g$  Tested



S:SOP-8L



Marking:12N02 OR 2012

### Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D @ T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	12	A
$I_D @ T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	7.8	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	44	A
$P_D @ T_A=25^\circ C$	Total Power Dissipation <sup>3</sup>	3	W
$P_D @ T_A=70^\circ C$	Total Power Dissipation <sup>3</sup>	0.86	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Data

Symbol	Parameter	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	100	$^\circ C/W$

**TM12N02S**
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**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	20	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=20\text{V}$ , $V_{GS}=0\text{V}$ ,	-	-	1.0	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 12\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$	0.5	0.75	1.2	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS}=4.5\text{V}$ , $I_D=15\text{A}$	-	8	11	$\text{m}\Omega$
		$V_{GS}=2.5\text{V}$ , $I_D = 10\text{A}$	-	11	13	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=10\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	868	-	pF
$C_{oss}$	Output Capacitance		-	182	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	164	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=10\text{V}$ , $I_D=15\text{A}$ , $V_{GS}=4.5\text{V}$	-	15	-	nC
$Q_{gs}$	Gate-Source Charge		-	2	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	5.2	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=10\text{V}$ , $I_D=15\text{A}$ , $R_{\text{GEN}}=3\Omega$ , $V_{GS}=4.5\text{V}$	-	9	-	ns
$t_r$	Turn-on Rise Time		-	25	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	37	-	ns
$t_f$	Turn-off Fall Time		-	14	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	12	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	44	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s=30\text{A}$	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition:  $T_J=25^\circ\text{C}$ ,  $V_{DD}=10\text{V}$ ,  $V_G=4.5\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_G=25\Omega$ ,  $I_{AS}=9.6\text{A}$

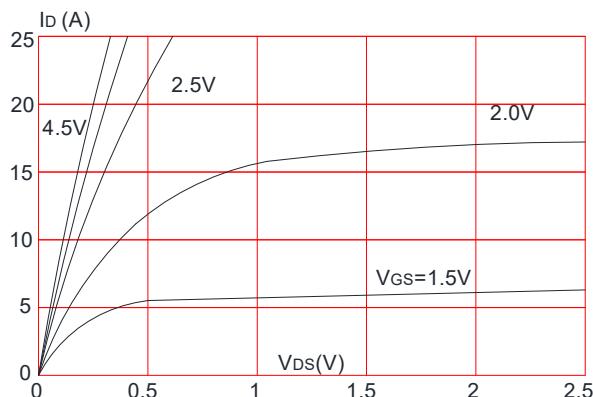
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$

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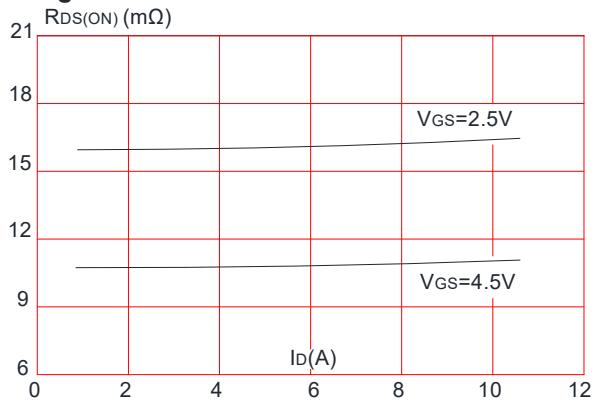
## N-Channel Enhancement Mosfet

### Typical Performance Characteristics

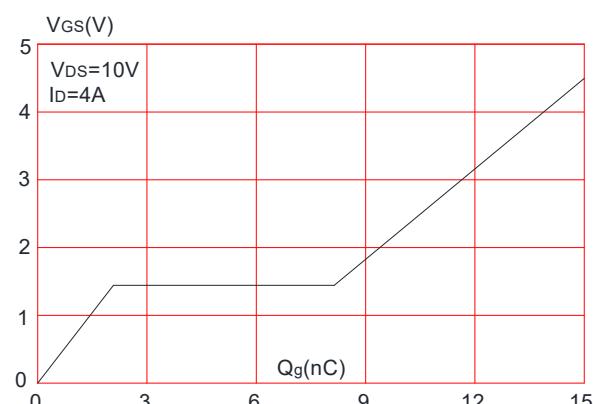
**Figure 1:** Output Characteristics



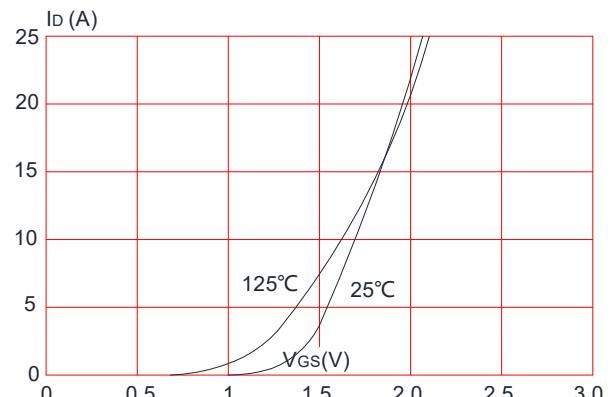
**Figure 3:** On-resistance vs. Drain Current



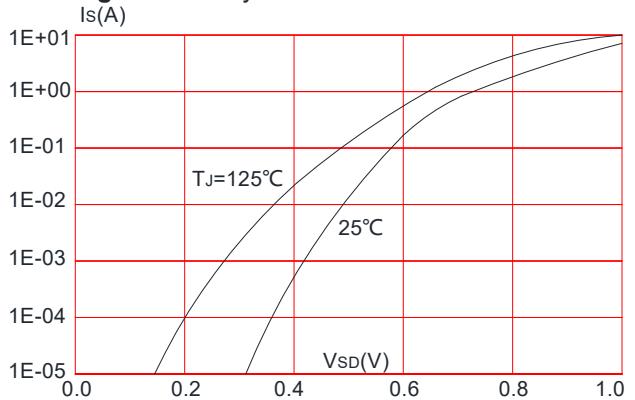
**Figure 5:** Gate Charge Characteristics



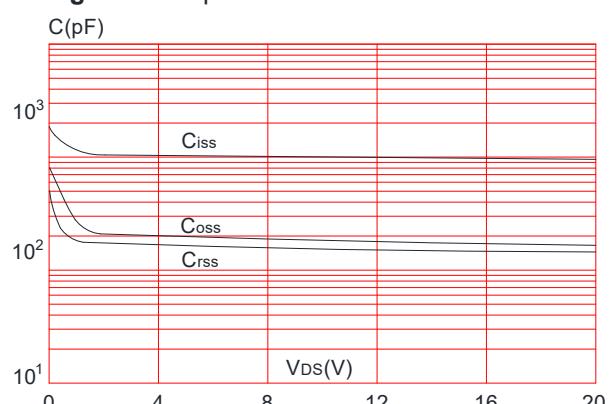
**Figure 2:** Typical Transfer Characteristics



**Figure 4:** Body Diode Characteristics



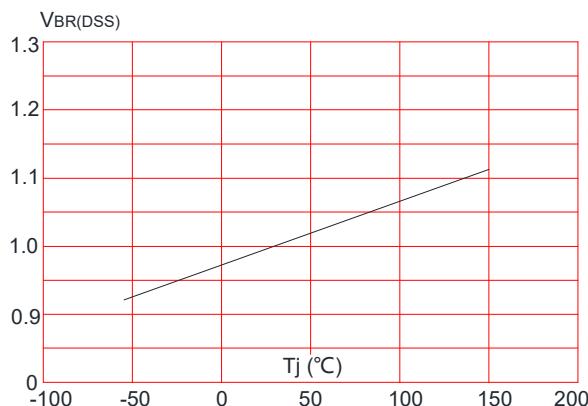
**Figure 6:** Capacitance Characteristics



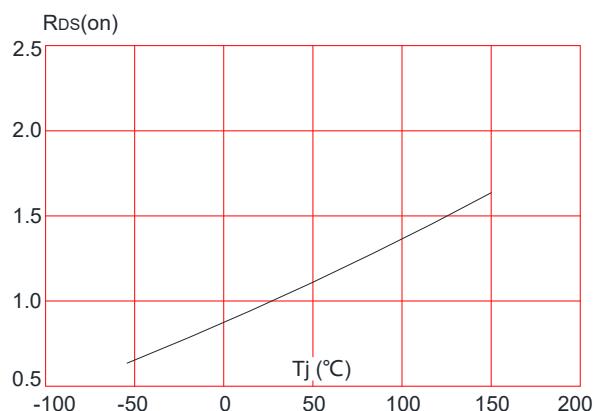
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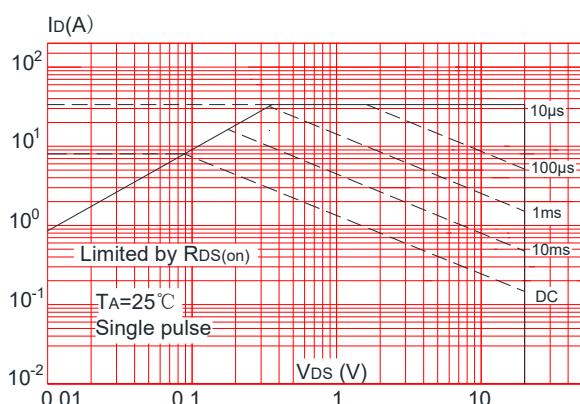
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



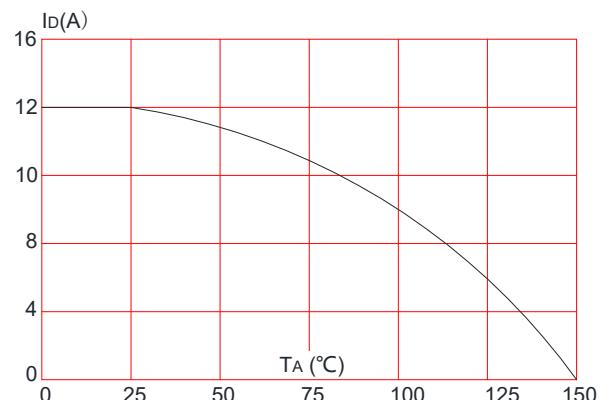
**Figure 8:** Normalized on Resistance vs. Junction Temperature



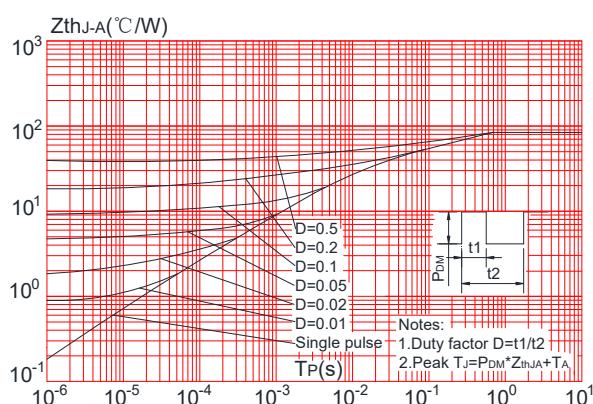
**Figure 9:** Maximum Safe Operating Area



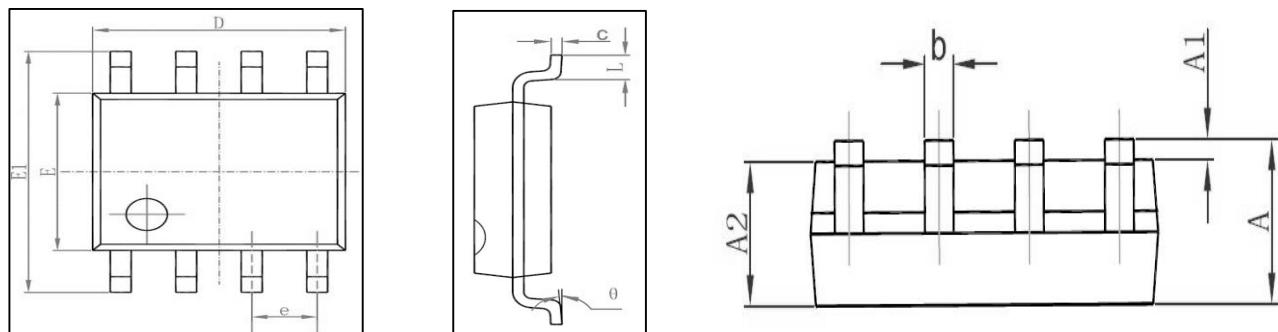
**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



## Package Mechanical Data:SOP-8L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

